



CERTIFICATE OF ACCREDITATION

ANSI-ASQ National Accreditation Board

500 Montgomery Street, Suite 625, Alexandria, VA 22314, 877-344-3044

This is to certify that

SMT Corporation
14 High Bridge Road
Sandy Hook CT 06482

has been assessed by ANAB
and meets the requirements of international standard

ISO/IEC 17025:2005

while demonstrating technical competence in the field of

TESTING

Refer to the accompanying Scope of Accreditation for information regarding the types of tests to which this accreditation applies.

AT-1733
Certificate Number


ANAB Approval

Certificate Valid: 10/21/2016-10/22/2018
Version No. 002 Issued: 10/21/2016



This laboratory is accredited in accordance with the recognized International Standard ISO/IEC 17025:2005. This accreditation demonstrates technical competence for a defined scope and the operation of a laboratory quality management system (refer to joint ISO-ILAC-IAF Communiqué dated January 2009).



ANSI-ASQ National Accreditation Board

SCOPE OF ACCREDITATION TO ISO/IEC 17025:2005

SMT Corporation

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TESTING

Valid to: October 22, 2018

Certificate Number: AT - 1733

FIELD OF TEST	ITEMS, MATERIALS OR PRODUCTS TESTED	SPECIFIC TESTS OR PROPERTIES MEASURED	SPECIFICATION, STANDARD METHOD OR TECHNIQUE USED	*KEY EQUIPMENT OR TECHNOLOGY
Non-Destructive Testing (NDT) (Inspection)	Electrical, Electronic and Electromechanical (EEE) Components	Radiographic Examination / Inspection	Internal Procedure: W750-15 IDEA-STD-1010B AS6081	Glenbrook Jewel-box 90T
Destructive Testing (NDT) (Inspection)	Electrical, Electronic and Electromechanical (EEE) Components	Scanning Electron Microscopy (SEM) Examination / Inspection	Internal Procedure: W750-12 IDEA-STD-1010B AS6081	Tescan
Non-Destructive Testing (NDT) (Inspection)	Electrical, Electronic and Electromechanical (EEE) Components	Visual Inspection	Internal Procedure: W750-18 IDEA-STD-1010B AS6081	Dinocapture 2.0 To 230x
Mechanical (Inspection)	Electrical, Electronic and Electromechanical (EEE) Components	Resistance to Solvents (RTS) / Scrape Test	Internal Procedure: W750-11 IDEA-STD-1010B AS6081	Removal of Residue
Mechanical (Inspection)	Electrical, Electronic and Electromechanical (EEE) Components	Packaging Configuration and Dimensions	Internal Procedure: W750-19 MIL-STD-883 Method 2016 IDEA-STD-1010B AS6081	Calipers Device to print Package Dimensions
Mechanical	Electrical, Electronic and Electromechanical (EEE) Components	Dynasolve	Internal Procedure: W750-09 IDEA-STD-1010B AS6081	Removal of Residue
Mechanical (Inspection)	Electrical, Electronic and Electromechanical (EEE) Components	Decapsulation and Die Verification	Internal Procedure: W750-21 IDEA-STD-1010B AS6081	Nisene Jet-Etch Acid Decapsulator



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Electrical (Inspection)	Electrical, Electronic and Electromechanical (EEE) Components	Capacitance Measurement	MIL-STD-202G METHOD 305A Internal Procedure: W750-03	LCR Meter – Quadtech 7600B
Electrical (Inspection)	Electrical, Electronic and Electromechanical (EEE) Components	Contact Resistance	MIL-STD-202 Method 307 Internal Procedure: W750-02	Multimeter
Electrical Testing	Diodes	Forward voltage drop	MIL-STD-750 METHOD 4011 Internal procedure: W750-4011.4	PXI-4130 Source-Measure Unit PXI-4072 DMM, PXI-5122 Digitizer (Oscilloscope) PXIe-6556 Digital Waveform Generator
Electrical Testing	Diodes	Reverse Current Leakage	MIL-STD-750 METHOD 4016 Internal procedure: W750-4016.4	PXI-4130 Source-Measure Unit
Electrical Testing	Zener Diodes	Regulator (breakdown) Voltage	MIL-STD-750 METHOD 4022 Internal procedure: W750-4022	PXI-4130 Source-Measure Unit PXI-4072 DMM
Electrical Testing	Microcircuits	Propagation Delay	MIL-STD-883 METHOD 3003 Internal procedure: W883-3003	PXI-4110 Power Supply PXI-6556 Digital Waveform Generator LeCroy WavePro 7300A 3GHz Oscilloscope
Electrical Testing	Microcircuits	Power Supply Current	MIL-STD-883 METHOD 3005 Internal procedure: W883-3005	PXI-4130 Source-Measure Unit PXI-4110 Power Supply PXI-4072 DMM
Electrical Testing	Microcircuits	High Level Output Voltage	MIL-STD-883 METHOD 3006 Internal procedure: W883-3006	PXI-4130 Source-Measure Unit PXI-4110 Power Supply PXI-4072 DMM
Electrical Testing	Microcircuits	Low Level Output Voltage	MIL-STD-883 METHOD 3007 Internal procedure: W883-3007	PXI-4130 Source-Measure Unit PXI-4110 Power Supply PXI-4072 DMM
Electrical Testing	Microcircuits	Low Level Input Current	MIL-STD-883 METHOD 3009 Internal procedure: W883-3009	PXI-4130 Source-Measure Unit PXI-4110 Power Supply PXI-4072 DMM

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Electrical Testing	Microcircuits	High Level Input current	MIL-STD-883 METHOD 3010 Internal procedure: W883-3010	PXI-4130 Source-Measure Unit PXI-4110 Power Supply PXI-4072 DMM
Electrical Testing	Microcircuits	Output Short Circuit Current	MIL-STD-883 METHOD 3011 Internal procedure: W883-3011	PXI-4130 Source-Measure Unit PXI-4110 Power Supply PXI-4072 DMM
Electrical Testing	Microcircuits	Functional Testing	MIL-STD-883 METHOD 3014 Internal procedure: W883-3014	PXI-4110 Power Supply PXI-6556 Digital Waveform Generator
Electrical Testing	Microcircuits	Input Clamp Voltage	MIL-STD-883 METHOD 3022 Internal procedure: W883-3022	PXI-4130 Source-Measure Unit PXI-4110 Power Supply PXI-4072 DMM

Notes:

1. * = As Applicable
2. This scope is formatted as part of a single document including the Certificate of Accreditation No. AT-1733



 Vice President